

General Description

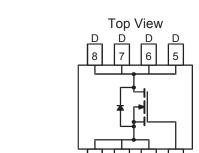
The AAT9501 is a low threshold MOSFET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s utra high density MOSFET process and space saving small outline J-lead package, performance superior to that normally found in a TSOP-6 footprint has been squeezed into the footprint of a SC70 package.

Features

- $V_{DS(MAX)} = 25V$

- $I_{D(MAX)}^{1} = 6.5A @ 25^{\circ}C$ Low $R_{DS(ON)}^{1}$: 24 m Ω @ $V_{GS} = 4.5V$
 - 40 mΩ @ V_{GS} = 2.5V

SC70JW-8 Package



Applications

- Battery packs
- Cellular & Cordless Telephones
- Battery-powered portable equipment

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V _{DS}	Drain-Source Voltage		25	V	
V _{GS}	Gate-Source Voltage		±12		
I _D	Continuous Drain Current @ T _J =150°C ¹	T _A = 25°C	±6.5		
		T _A = 70°C	±5.2	Α	
I _{DM}	Pulsed Drain Current		±32	A	
I _S	Continuous Source Current (Source-Drain Diode) 1		1.5		
P_{D}	Maximum Power Dissipation ¹	$T_A = 25^{\circ}C$	1.7	W	
		T _A = 70°C	1.0	V V	
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C	

Thermal Characteristics

Symbol	Description	Тур	Max	Units
$R_{\theta JA}$	Junction-to-Ambient steady state ¹	100	120	
$R_{\theta JA2}$	Junction-to-Ambient, t<5 sec. 1	61	73.5	°C/W
$R_{\theta JF}$	Junction-to-Foot 1	33	40	



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units
DC Charac	DC Characteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V, I_D =250 μ A	25			V
R _{DS(ON)}	Drain-Source ON-Resistance ²	V_{GS} =4.5V, I_D =6.5A		19	24	- mΩ
		V_{GS} =2.5V, I_D =5.0A		31	40	11122
I _{D(ON)}	On-State Drain Current ²	V _{GS} =4.5V, V _{DS} =5V (Pulsed)	32			Α
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=250\mu A$	0.6			V
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
	Drain Source Leakage Current	V_{GS} =0V, V_{DS} =25V			1	μA
I _{DSS}		V_{GS} =0V, V_{DS} =20V, T_J =70°C ³			5	
g _{fs}	Forward Transconductance ²	V_{DS} =5V, I_D =6.5A		17		S
Dynamic C	Dynamic Characteristics ³					
Q_{G}	Total Gate Charge	V_{DS} =15V, R_{D} =2.7 Ω , V_{GS} =4.5V		13	19	
Q_{GS}	Gate-Source Charge	V_{DS} =15V, R_{D} =2.7 Ω , V_{GS} =4.5V		1.9		nC
Q_{GD}	Gate-Drain Charge	V_{DS} =15V, R_{D} =2.7 Ω , V_{GS} =4.5V		2.9		
t _{D(ON)}	Turn-ON Delay	V_{DD} =15V, V_{GS} =4.5V, R_{D} =2.7 Ω , R_{G} =6 Ω		15		
t _R	Turn-ON Rise Time	V_{DD} =15V, V_{GS} =4.5V, R_{D} =2.7 Ω , R_{G} =6 Ω		18		ns
t _{D(OFF)}	Turn-OFF Delay	V_{DD} =15V, V_{GS} =4.5V, R_{D} =2.7 Ω , R_{G} =6 Ω		36		115
t _F	Turn-OFF Fall Time	V_{DD} =15V, V_{GS} =4.5V, R_{D} =2.7 Ω , R_{G} =6 Ω		27		
Source-Dra	Source-Drain Diode Characteristics					
V _{SD}	Source-Drain Forward Voltage ²	V _{GS} =0, I _S =6.5A			1.3	V
I _S	Continuous Diode Current ¹				1.5	Α

Notes:

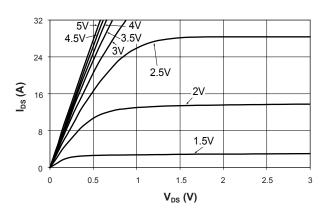
- 1. Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in many applications. $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$ where the foot thermal reference is defined as the normal solder mounting surface of the device's leads. $R_{\theta JF}$ is guaranteed by design, however $R_{\theta CA}$ is determined by the PCB design. Actual maximum continuous current is limited by the application's design.
- 2. Pulse test: Pulse Width = 300 μs
- 3. Guaranteed by design. Not subjected to production testing.



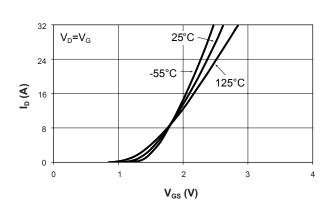
Typical Characteristics

 $(T_{.1} = 25^{\circ}\text{C unless otherwise noted})$

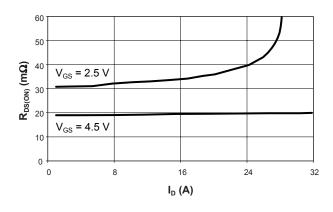
Output Characteristics



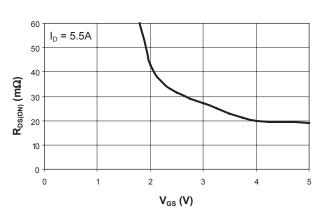
Transfer Characteristics



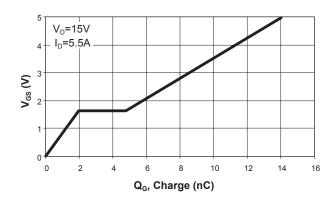
On-Resistance vs. Drain Current



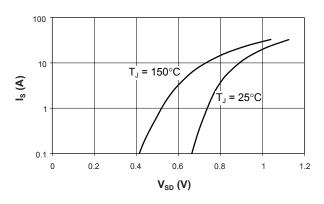
On-Resistance vs. Gate to Source Voltage



Gate Charge



Source-Drain Diode Forward Voltage





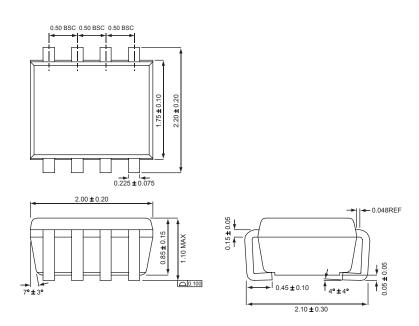
Ordering Information

Package	Marking ¹	Part Number (Tape and Reel)
SC70JW-8	FEXYY	AAT9501IJS-T1

Note: Sample stock is generally held on all part numbers listed in BOLD.

Note 1: XYY = assembly and date code.

Package Information



All dimensions in millimeters.

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